

In the claims:

Claims 1-10 cancelled.

11. (New) A method of producing a grinding or polishing pad, comprising the steps of providing a body which is substantially hard to form a hard backing for the pad and has a first curing agent; providing a working layer which is optionally provided with abrasive and has a second curing agent; providing a connecting layer between said body and said working layer so as to add said working layer to said body, which said connecting layer has a third curing agent; selecting a quantity of at least one of said first curing agent and said second curing agent which is reduced when compared with a conventional amount; providing in said connecting layer an amount of said third curing layer which substantially corresponds to said amount by which at least one of said first and second curing agents is reduced; and subjecting said body, said working layer and said connecting layer to a thermal treatment so that said third curing agent from said connecting layer migrates into said at least one of said body and said working layer so as to bring the amount of said at least one of said first and second curing agents to a conventional amount.

12. (New) A method as defined in claim 11, wherein an amount of said first curing agent in said body and an amount of said curing in said

working layer are reduced from conventional amounts, while an amount of said curing agent in said connecting layer substantially corresponds to an amount by which the amount of said first curing agent and said second curing agent are reduced so that said third curing agent migrates into said body and into said working layer to bring the amount of said first curing agent and the second curing agent in said body and in said working layer to conventional amounts.

13. (New) A method as defined in claim 11, wherein the amount of at least one of said first and second curing agents in at least one of said body and said working layer is reduced by 75-80 % of the conventional amount, while the amount.

14. (New) A method as defined as defined in claim 11, wherein the amount of the first and second curing agents in said body and in said working layer is reduced by 75-80% as the compared with the conventional amounts.

15. (New) A grinding or polishing pad, comprising a body which is substantially hard to form a hard backing for the pad and has a first curing agent; a working layer which is optionally provided with abrasive and has a second curing agent; a connecting layer between said body and said working layer so as to connect said working layer to said body, which said connecting

layer has a third curing agent, wherein a quantity of at least one of said first curing agent and said second curing agent is reduced when compared with a conventional amount; wherein in said connecting layer an amount of said third curing layer substantially corresponds to said amount by which at least one of said first and second curing agents is reduced, so that when said body, said working layer and said connecting layer are subjected to a thermal treatment said third curing agent from said connecting layer migrates into said at least one of said body and said working layer so as to bring the amount of said at least one of said first and second curing agents to a conventional amount.

16. (New) A grinding or polishing pad as defined in claim 13, wherein an amount of said first curing agent in said body and an amount of said curing agent in said working layer are reduced from conventional amounts, while an amount of said curing agent in said connecting layer substantially corresponds to an amount by which the amount of said first curing agent and said second curing agent are reduced so that said third curing agent migrates into said body and into said working layer so as to bring the amount of said first curing agent and the second curing agent in said body and in said working layer to conventional amounts.

17. (New) A method as defined in claim 15, wherein the amount of one of said first and second curing agents in at least one of said body and said working layer is reduced by 75-80 % of the conventional amount.

18. (New) A method as defined as defined in claim 15, wherein the amount of the first and second curing agents in said body and in said working layer is reduced by 75-80% compared with the conventional amounts.